



BFF1113 Engineering Materials



DR. NOOR MAZNI ISMAIL FACULTY OF MANUFACTURING ENGINEERING



Course Guidelines:

- 1. Introduction to Engineering Materials
- 2. Bonding and Properties
- 3. Crystal Structures & Properties
- 4. Imperfection in Solids
- 5. Mechanical Properties of Materials
- 6. Physical Properties of Materials
- 7. Failure & Fundamental of Failure
- 8. Metal Alloys
- 9. Phase Diagram
- 10. Phase Transformation Heat Treatment
- 11. Processing and Application of Metals
- 12. Ceramic Materials
- 13. Polymer Materials
- 14. Composite Materials
- 15. Corrosion & Degradation of Materials
- 16. Environment and Sustainability





Bonding and Properties

- **1. Atomic structure and bonding**
- 2. Crystal structures and properties
- 3. Crystalline and non-crystalline materials
- 4. Imperfection in solids

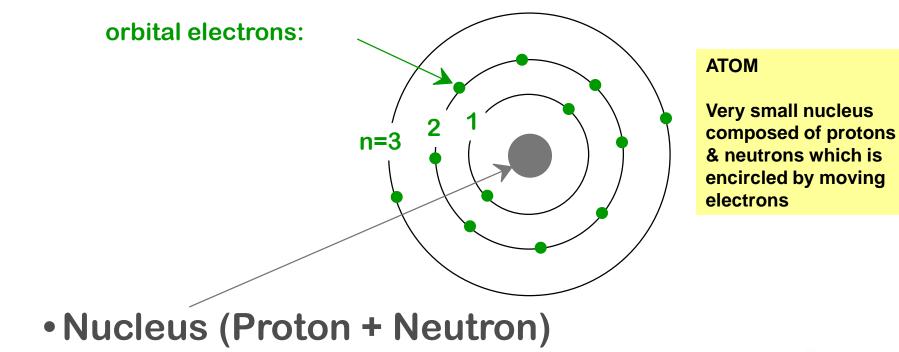




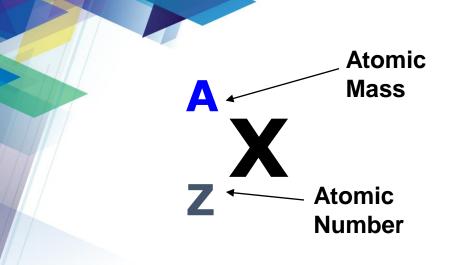
ATOMIC MODELS

Simplified Atomic Model

Some Terminologies (basic structure for elements)









Atomic mass (A) \approx Z + N

• Z (atomic number) = # protons

• N = # neutrons

Example:

Determine the number of Proton, electron and neutron in a fluorine atom.

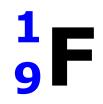
Answer:

A = p + n = 19

$$Z = p = e = 9$$

→ n = A - Z =
$$19 - 9 = 10$$

- Proton = 9
- Electron = 9
- Neutron = 10







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The mass and charge of Proton, Neutron, and Electron

	Mass (g)	Charge (C)
Proton	1.673 x 10 ⁻²⁴	+1.602 x 10 ⁻¹⁹
Neutron	1.675 x 10 ⁻²⁴	0
Electron	9.109 x 10 ⁻²⁸	-1.602 x 10 ⁻¹⁹



1. INTERATOMIC BONDING

Why we need to understand the concept of interatomic bonding in solids?

Some important properties of solid depend on geometrical atomic arrangements & also the interactions that exist among constituent atoms or molecules

Example: Carbon ~ graphite & diamond





Interatomic

Primary Bonding

- Ionic bonds
- Covalent bonds
- Metallic bonds

Secondary Bonding

- Van der Waals bonds
- Hydrogen bond





3 different types of **primary** or chemical bond are found in solids.

- lonic, covalent, and metallic.
- Involve valence electrons
- Nature of bond depends on electron structures of the constituent atoms.

Tendency of atoms to assume stable electron structure.

- Secondary (or physical) forces and energies also found in many solid materials.
 - Wan Der Waals, Hydrogen bond
 - Weaker than primary ones
 - Influence physical properties of some material





1.1: Primary Interatomic Bonds

- Primary Bonding > Ionic Bonding
 - > Covalent Bonding
 - > Metallic Bonding





Ionic Bonding

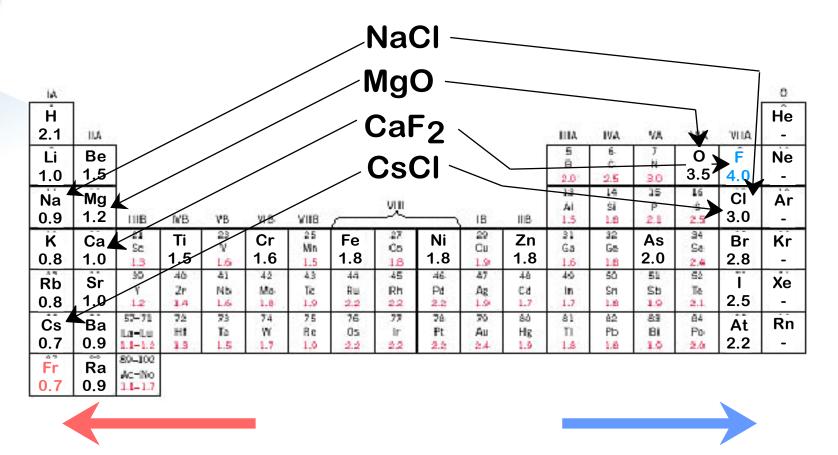
- Formed between highly electropositive (metallic) elements and highly electronegative (nonmetallic) elements.
- Ionization: <u>electrons are transferred</u> from atoms of electropositive elements to atoms of electronegative elements, producing positively charged cations and negatively charge anions.
- Ionic bonding: due to electrostatic / coulombic force attraction of oppositely charged ions.
- **Binding energy** \rightarrow large \rightarrow high melting temp.
- Ionic material \rightarrow hard, brittle, electrically and thermally insulative.



EXAMPLES: IONIC BONDING



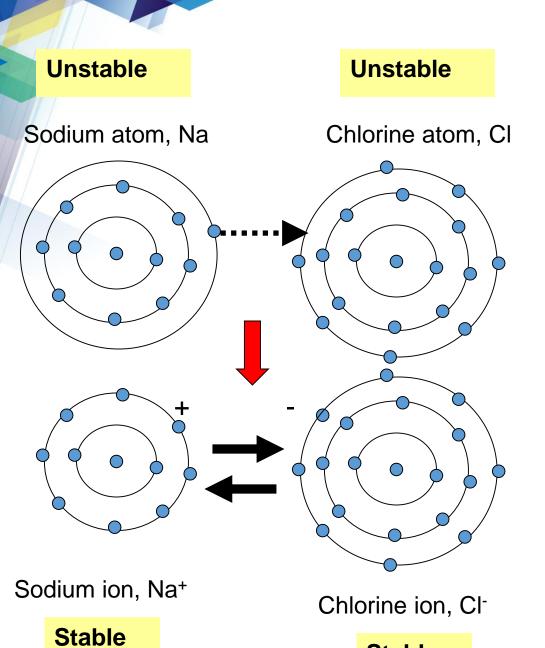
Predominant bonding in Ceramics •



Give up electrons (electropositive)

Acquire electrons (electronegative)

Adapted from Fig. 2.7, Callister 6e. (Fig. 2.7 is adapted from Linus Pauling, The Nature of the Chemical Bond, 3rd edition, Copyright 1939 and 1940, 3rd edition. Copyright 1960 by Cornell UMP OPEN **University**



Stable



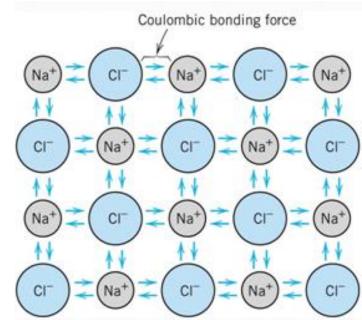


FIGURE 2.9 Schematic representation of ionic bonding in sodium chloride (NaCl).



Covalent Bonding

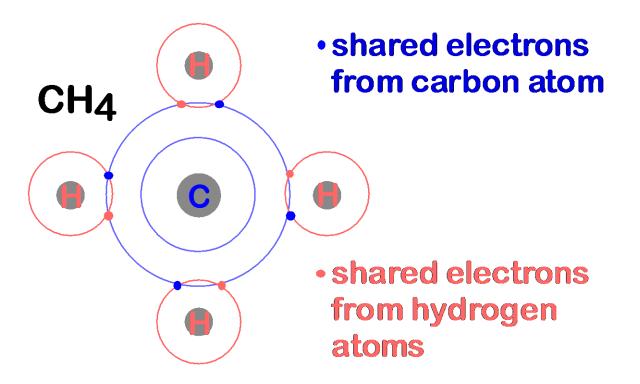
- In covalent bonding stable electron configurations are assumed by <u>sharing of electrons</u> between adjacent atoms.
- Two atoms that are covalently bonded will each contribute at least one electron to the bond, and the shared electrons may be considered to belong to both atoms.
- $\blacksquare H \bullet + H \bullet \rightarrow H:H \quad (1s^1 \text{ electron from hydrogen atom})$
- Many nonmetallic elemental molecules (H₂, Cl₂, F₂, etc)
- Molecules containing dissimilar atoms (CH₄, H₂O, HNO₃, HF, etc)
- Other elemental solids: diamond (carbon), silicon, germanium
- Binding energy & melting temp for covalently bonded materials → very high (diamond) to very weak (bismuth, polymeric material)
 - Possible of having interatomic bonds (partially ionic and partially covalent).





• Example: CH₄ (methane)

C: has 4 valence e, needs 4 more H: has 1 valence e, needs 1 more





EXAMPLES: COVALENT BONDING



UMP OPEN

1		•-						420	0				IVA					
IA		12				C	C(di	ian	non	nd).			umn l			,	0	F ₂
H 4 2.1 Li 1.0	Be 1.5]						SiC				5 0	00 C 2.5	7 N 30	VIA 0 2.0	VIA F 4.0	He - Ne	Cl ₂
Na 0.9	Mg 1.2	HIB	NB	٧B	VI B-	VIIB	_	<u>_v</u>		IB	IIB	14 Al 1.5	Si 1.8	15 P 2.1	16 \$ 2.5	CI 3.0	Ar -	
K 0.8	Ca 1.0	21 Sc 1.3	Ti 1.5	23 V L.6	Cr 1.6	25 Min 1.5	Fe 1.8	27 Co 18	Ni 1.8	29 Cu 1.9	Zn 1.8	Ga 1.6	Ge 1.8	As 2.0	34 Se 2.4	Br 2.8	Kr -	
Rb 0.8	Sr 1.0	30 Υ 1.2	46 2r 1.4	41 Nb 1.6	42 Mo 1.8	43 Te 1.9	44 Ru 2.2	45 Rh 2.2	46 Pđ 2.2	47 Ag 1.9	48 C.8 1.7	40 In 1.7	Sn 1.8	Sb 1.9	52 Te 2.1	Î 2.5	Xe -	
Cs 0.7	Ba 0.9	57-71 La-Lu 1.1-1.2	72 H1 1.9	73 Ta 1.5	74 W 1.7	75 Re 1.0	76 05 2.2	77 Ir 22	78 Pt 2.2	70 Au 2.4	80 Hg 1.9	81 11 1.8	∀b/ 1.8	83 Bi 1.0	84 Po 2.0	At 2.2	Rn -	
Fr 0.7	Ra 0.9	89-102 Ac-No 11-17	ŝ						-			(Gal	As				

- Molecules with nonmetals
- Molecules with dissimilar atoms
- Elemental solids (RHS of Periodic Table)
- Compound solids (about column IVA) (SiC, GaAs)

Adapted from Fig. 2.7, Callister 6e. (Fig. 2.7 is

adapted from Linus Pauling, *The Nature of the Chemical Bond*, 3rd edition, Copyright 1939 and 1940, 3rd edition. Copyrigh 1960 by Cornell University.

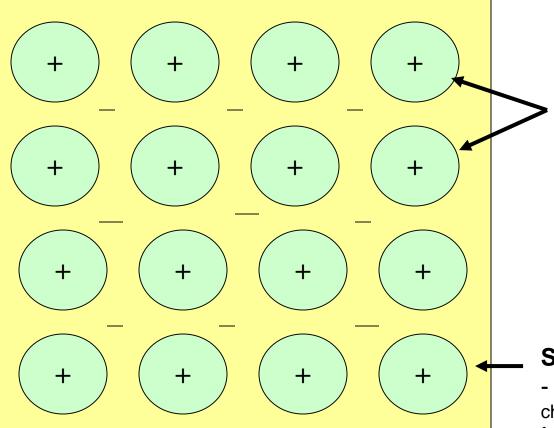
Metallic Bonding

- Very similar to covalent bonding
- Valence electrons
 - Metallic materials have 1, 2, or 3 valence electrons.
 - not bound to any particular atom in the solid.
 - are essentially free electrons and move (drift) through out the metal.
 - form a sea of electron or electron cloud.
- Remaining non-valence electrons and atomic nuclei
 ion cores
- Group IA and IIA elements
- All elemental metals
- Highly conductive
- Ductile,
- Binding energy & melting temp (wide range)





Schematic illustration of metallic bonding



lon cores

- nonvalence electrons and atomic nuclei

-posses a net positive charge equal in magnitude to the total valence electron charge per atom.

Sea of valence electrons

- The free electrons shield the positively charged ion chores from electrostatic forces.

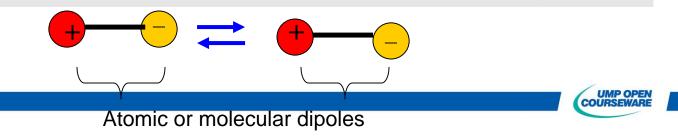
- This free electrons act as a "glue" to hold the ion cores together.



1.2: Secondary Bonds Van der Waals Bonds

- Van der Waals bond or physical bond
- Binding energy (typical) \rightarrow in the order of 10 kJ/mol (0.1 eV/atom)
- Exist between virtually all atoms or molecules.
- The presence of any of the 3 primary bonding types may obscure it.
- The driving force for secondary bonding is the attraction of the electric dipoles contained in atoms or molecules
- Electric dipoles:
 - separation of positive and negative portions of an atom or molecule. coulombic attraction between +ve end of one dipole and –ve end dipole.

Schematic illustration of van der Waals bonding between two dipoles



Bonding Energies and Melting Temperatures for Various Substances

				Universiti
Bonding Type		Bonding	Melting Temperature	
	Substance	kJ/mol	kJ/mol eV/atom, ion, molecule	
lonic	NaCl	640	3.3	801
	MgO	1000	5.2	2800
Covelent	Si	450	4.7	1410
	C (diamond)	713	7.4	>3550
Metallic	Hg	68	0.7	-39
	AI	324	3.4	660
	Fe	406	4.2	1538
	W	849	8.8	3410
Van der Waals	Ar	7.7	0.08	-189
	Cl ₂	31	0.32	-101
l h . da	NH_3	35	0.36	-78
Hydrogen	H ₂ O	51	0.52	





HYDROGEN BONDS

THINK....

WHY ICE CUBES FLOAT IN WATER





2.0 Crystal Structures & Properties3.0 Crystalline and non-crystalline materials

- Introduction
- Arrangement of atom in metallic crystal structures
- Single crystal, polycrystalline materials
- X-ray diffraction: determination of crystal structure





At the end of the lecture, students will be able:

- 1. To describe the difference in atomic/molecular structure between crystalline and noncrystalline materials.
- 2. To draw unit cells for face-centered cubic (FCC), bodycentered cubic (BCC), and hexagonal close-packed crystal (HCP) structures.
- 3. To derive the relationships between unit cell edge length and atomic radius for FCC and BCC crystal structures.
- 4. To compute the densities for metals having FCC and BCC crystal structures given their unit cell dimensions.
- 5. To distinguish between single crystals and polycrystalline materials.
- 6. To describe briefly the use of XRD to identify an element.





ARRANGEMENT OF ATOMS

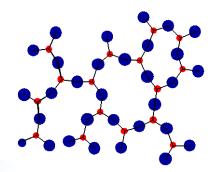
Solid materials:

- Classified according to the <u>regularity</u> with which <u>atoms or ions are arranged</u> with respect to one another.
- 2 types:
 - Crystalline materials
 - Noncrystalline (or amorphous) materials

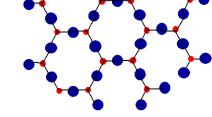


Noncrystalline vs. crystalline SiO₂





• Si Oxygen



noncrystalline SiO₂

Noncrystalline materials...

- atoms have no periodic or repeating packing (not systematic).
- has no long range atomic order. occurs for: -complex structures, -rapid cooling

"Amorphous" = Noncrystalline

crystalline SiO₂

Crystalline materials...

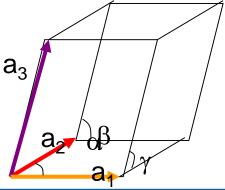
- atoms pack in periodic (or repeating), over large atomic distances (long range order)
- typical of: -metals, -many ceramics, some polymers

Note: There is an extremely large number of different crystal structures all having long range atomic order, depending how you ARRANGE and PACK it.



How many types of crystal structures are available?

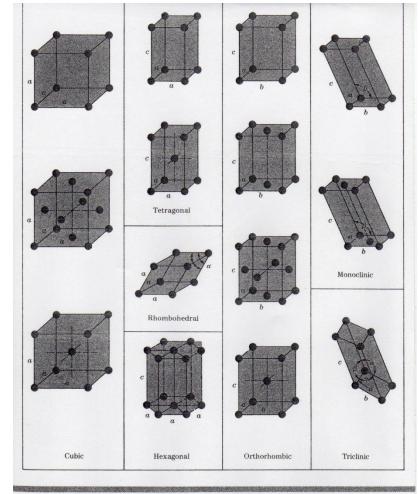
- How many types of unit cell? (Unit cell small repeat entities) ***Smallest group of atoms showing the lattice structure is known as a unit cell
- Depends on types of lattices (3D array of point coinciding with atom positions)
- There is an unlimited number of possible lattices because there is no natural restriction on the <u>lengths of lattice</u> <u>translation vectors</u> or on the <u>angle φ</u> between them.
- 3 primary directional length + 3 angles between the 3 directions → type of unit cell





Crystal system	Restriction on conventional cell axes and angles
Triclinic	$a_1 \neq a_2 \neq a_3$ $\alpha \neq \beta \neq \gamma$
Monoclinic	$a_{1} \neq a_{2} \neq a_{3}$ $\alpha = \gamma = 90^{\circ} \neq \beta$
Orthorhombic	$a_1 \neq a_2 \neq a_3$ $\alpha = \gamma = \beta = 90^{\circ}$
Tetragonal	$a_1 = a_2 \neq a_3$ $\alpha = \gamma = \beta = 90^{\circ}$
Cubic	$a_1 = a_2 = a_3$ $\alpha = \gamma = \beta = 90^{\circ}$
Trigonal	$a_1 = a_2 = a_3$ $\alpha = \beta = \gamma < 120^{\circ}, \neq 90^{\circ}$
Hexagonal	$a_1 = a_2 \neq a_3$ $\alpha = \beta = 90^{\circ}$
	γ = 120°





GURE 3.2 The 14 Bravais conventional unit cells grouped according to crystal system. The dots indicate thice points that, when located on faces or at corners, are shared by other identical lattice unit cells. After W. G. Motfatt, G. W. Pearsall, and J. Wulff, "The Structure and Properties of Materials," vol. 1: Structure," Wiley, 1964, p. 47.)



The Crystal Structure of Metals

• have the simplest crystal structures.

3 basic atomic arrangements:

- 1. Face-centered cubic (fcc)
- 2. Body-centered cubic (bcc)
- 3. Hexagonal close-packed (hcp)

FYI only: SIMPLE CUBIC STRUCTURE (SC)



- Rare due to poor packing (only Polonium has this structure)
- Close-packed directions at cube edges (1 unit cell).



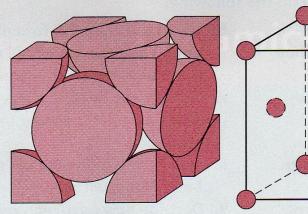


Assumptions used to describe crystal structure:

- When describing crystalline structures, atoms (or ions) are thought of as being solid spheres having well defines diameters (2 R).
- This is termed the atomic hard sphere model in which spheres representing nearest-neighbor atoms touch one another.



FACE CENTERED CUBIC STRUCTURE (FCC)



(a)

(b)

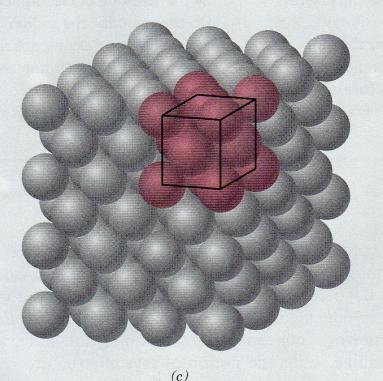


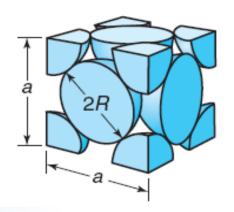
Figure 3.1 For the facecentered cubic crystal structure: (a) a hard sphere unit cell representation, (b) a reducedsphere unit cell, and (c) an aggregate of many atoms. (Figure (c) adapted from W. G. Moffatt, G. W. Pearsall, and J. Wulff, The Structure and Properties of Materials, Vol. I, Structure, p. 51. Copyright © 1964 by John Wiley & Sons, New York. Reprinted by permission of John Wiley & Sons, Inc.)

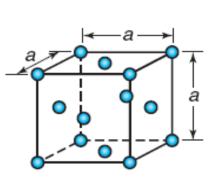
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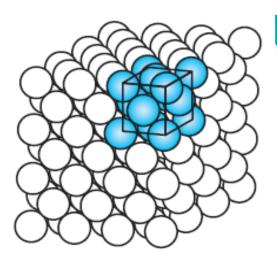


6 atom locate at surface (shared), 8 at corners (shared).







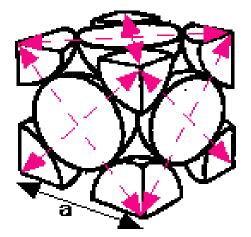




Hard-ball model

Unit cell

Single crystal with many unit cells



Equivalent number of atom

- = <mark>6</mark> x 1/2 + 1/8 x <mark>8</mark>
- = 4 atom/unit

a = the cube edge length





CALCULATIONS:

1)VOLUME OF CELL

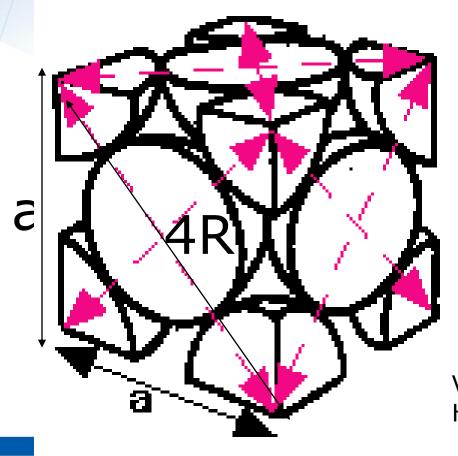
2)ATOMIC PACKING FACTOR



Example 1:



Calculate the volume of a FCC cell with atomic radius of R.



$$a^{2} + a^{2} = (4R)^{2}$$

 $a = 4R/\sqrt{2}$

Volume =
$$a^3$$

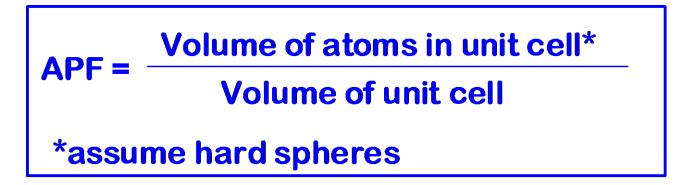
= $(4R/\sqrt{2})^3$

Volume = Width x Length x Height





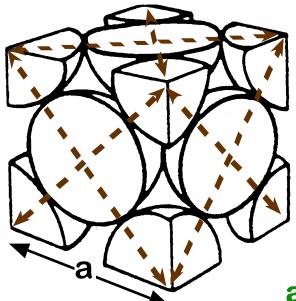
ATOMIC PACKING FACTOR (Fraction of spaced occupied by atoms)





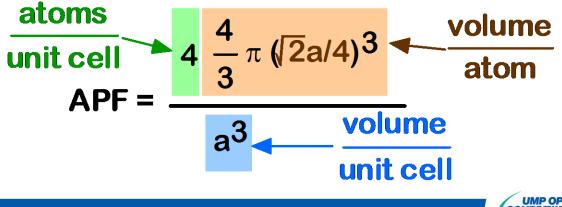
ATOMIC PACKING FACTOR: FCC

• APF for a face-centered cubic structure = 0.74



Close-packed directions: length = 4R = $\sqrt{2}$ a

Unit cell contains: 6 x 1/2 + 8 x 1/8 = 4 atoms/unit cell



Example 2:



Prove that the APF of FCC = 0.74, in term of the atomic radius, R:

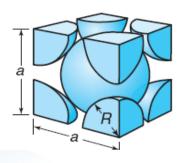
APF = V atom/ V unit cell V atom = $(4)(4/3\pi R^3) = 16.757R^3$ V unit cell = a^3 = $(4R/\sqrt{2})^3$ = 22.63R³ APF = $16.757R^3/22.63R^3$

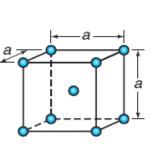
= 0.74



BODY CENTERED CUBIC STRUCTURE (BCC)



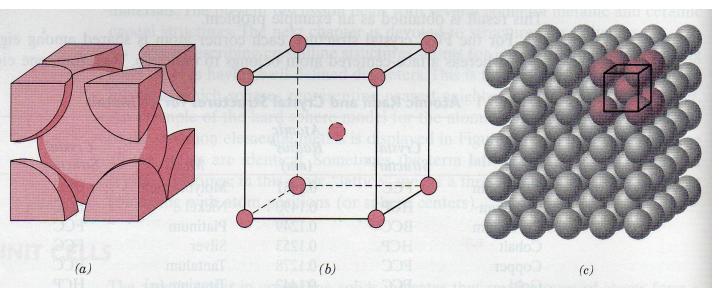




Hard-ball model



Single crystal with many unit cells



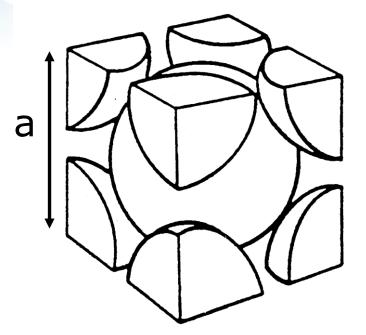
 1 atom locate at center, 8 at corners (shared)

Figure 3.2 For the body-centered cubic crystal structure, (a) a hard sphere unit cell representation, (b) a reduced-sphere unit cell, and (c) an aggregate of many atoms. (Figure (c) from W. G. Moffatt, G. W. Pearsall, and J. Wulff, *The Structure and Properties of Materials*, Vol. I, *Structure*, p. 51. Copyright © 1964 by John Wiley & Sons, New York. Reprinted by permission of John Wiley & Sons, Inc.)





CLASS ACTIVITY !!



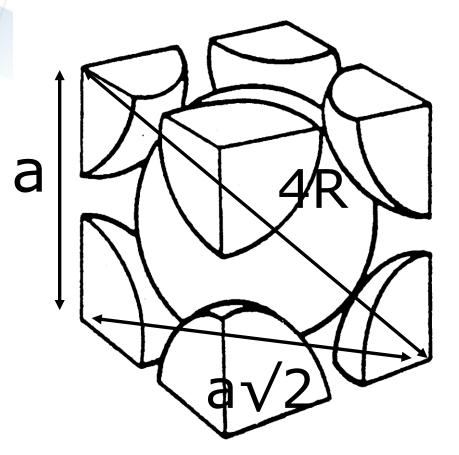
Calculate the volume of a BCC cell with atomic radius of R.



Example 2:



Calculate the volume of a BCC cell with atomic radius of R.



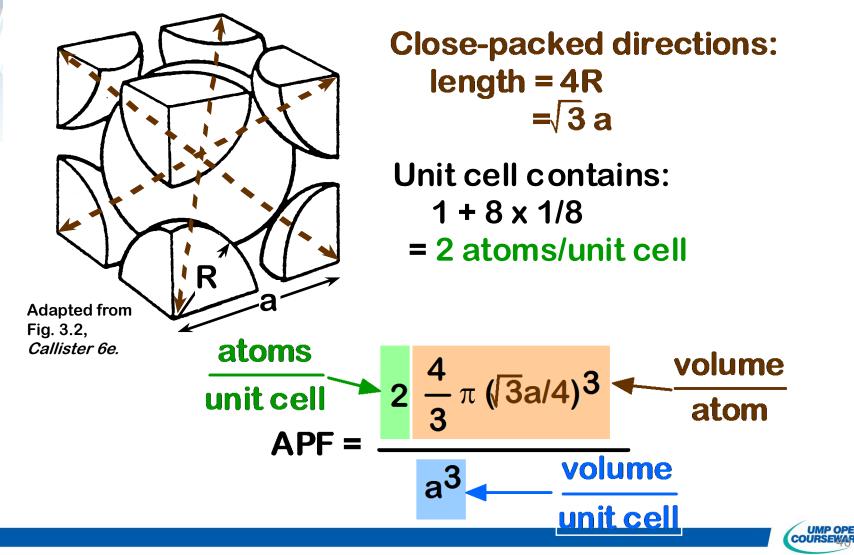
 $a^2 + (a\sqrt{2})^2 = (4R)^2$ $a = 4R/\sqrt{3}$

Volume = a^3 = $(4R/\sqrt{3})^3$



ATOMIC PACKING FACTOR: BCC

• APF for a body-centered cubic structure = 0.68



Example 3:



Prove the APF of BCC = 0.68

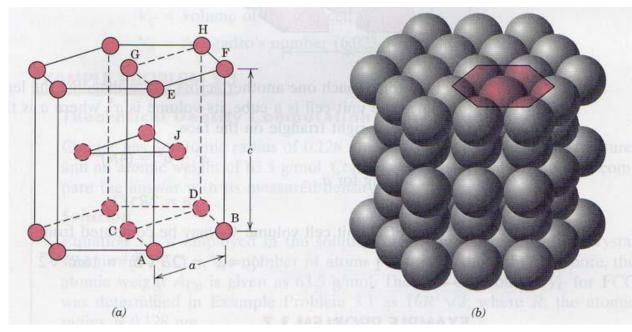
APF = V atom/ V unit cell V atom = $(2)(4/3\pi R^3) = 8.373R^3$ V unit cell = a^3 = $(4R/\sqrt{3})^3$ = $12.32 R^3$

APF = 8.373R³ / 12.32 R ³ = 0.68





HEXAGONAL CLOSE-PACKED STRUCTURE (HCP)



For HCP crystal structure, (a) a reduced-sphere unit cell: *a* and *c* represent the short and long edge lengths respectively) and (b) an aggregate (b) and (b) and (c) and (c

short and long edge lengths, respectively), and (b) an aggregate of many atom.

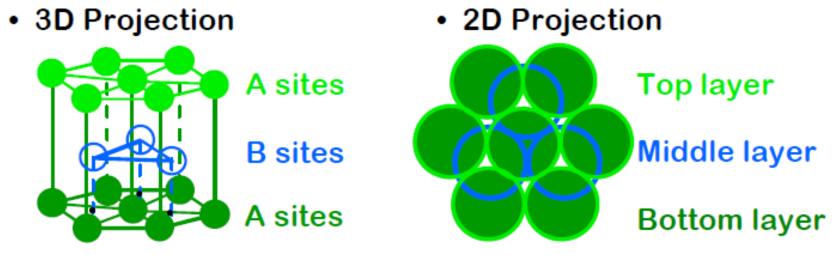
HCP crystals have the most densely packed configurations, followed by fcc and bcc

Arrangements can be modified by adding atoms of other metals known as **alloying**.





COURSEW



Adapted from Fig. 3.3, Callister 6e.

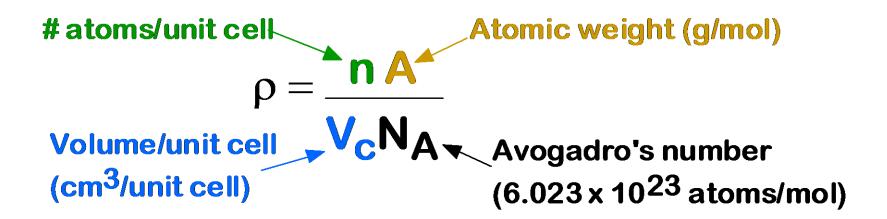
Number of atoms in a unit of HCP cell: No. atom/unit = 6

12 atoms at each corner/6 unit cell = 2
2 atoms at top and bottom of the hexagonal/2 = 1
3 atoms inside the hexagonal = 3

APF = 0.74



THEORETICAL DENSITY, ρ





Characteristics of Selected Elements at 20°C

Donaitu



			At. Weight	Density	Crystal	Atomic	radius
1	Element	Symbol	(amu)	(g/cm ³)	Structure	(nm)	
	Aluminum	AI	26.98	2.71	FCC	0.143	
	Argon	Ar	39.95				
	Barium	Ва	137.33	3.5	BCC	0.217	
	Beryllium	Ве	9.012	1.85	НСР	0.114	
	Boron	В	10.81	2.34	Rhomb		
	Bromine	Br	79.90				
	Cadmium	Cd	112.41	8.65	НСР	0.149	
	Calcium	Ca	40.08	1.55	FCC	0.197	
	Carbon	С	12.011	2.25	Hex	0.071	
	Cesium	Cs	132.91	1.87	BCC	0.265	
	Chlorine	CI	35.45				
	Chromium	Cr	52.00	7.19	BCC	0.125	
	Cobalt	Со	58.93	8.9	НСР	0.125	
	Copper	Cu	63.55	8.94	FCC	0.128	
	Flourine	F	19.00				
	Gallium	Ga	69.72	5.90	Ortho.	0.122	
	Germanium	Ge	72.59	5.32	Dia. cubic	0.122	
	Gold	Au	196.97	19.32	FCC	0.144	
	Helium	Не	4.003				
	Hydrogen	Η	1.008				UMP OPEN COURSEWARE

Example 4: Copper



Data from Table inside front cover of Callister (see next slide):

- crystal structure = FCC: 4 atoms/unit cell
- atomic weight = 63.55 g/mol (1 amu = 1 g/mol)
- atomic radius $R = 0.128 \text{ nm} (1 \text{ nm} = 10^{-7} \text{ cm})$
- Avogadro's number = 6.022 x 10²³ atoms/mol)

$$V_{c} = a^{3}$$
; For FCC, $a = 4R/\sqrt{2}$; $V_{c} = 4.75 \times 10^{-23} \text{ cm}^{3}$

$$\rho = \underline{nA} \\ V_c N_A$$

Result: theoretical ρ Cu = 8.89 g/cm³

EXAMPLE PROBLEM 3.3

Theoretical Density Computation for Copper

Copper has an atomic radius of 0.128 nm, an FCC crystal structure, and an atomic weight of 63.5 g/mol. Compute its theoretical density and compare the answer with its measured density.

Solution

Equation 3.5 is employed in the solution of this problem. Since the crystal structure is FCC, *n*, the number of atoms per unit cell, is 4. Furthermore, the atomic weight A_{Cu} is given as 63.5 g/mol. The unit cell volume V_C for FCC was determined in Example Problem 3.1 as $16R^3\sqrt{2}$, where *R*, the atomic radius, is 0.128 nm.

Substitution for the various parameters into Equation 3.5 yields

$$\rho = \frac{nA_{Cu}}{V_C N_A} = \frac{nA_{Cu}}{(16R^3\sqrt{2})N_A}$$

=
$$\frac{(4 \text{ atoms/unit cell})(63.5 \text{ g/mol})}{[16\sqrt{2}(1.28 \times 10^{-8} \text{ cm})^3/\text{unit cell}](6.023 \times 10^{23} \text{ atoms/mol})}$$

= 8.89 g/cm³

The literature value for the density of copper is 8.94 g/cm³, which is in very close agreement with the foregoing result.

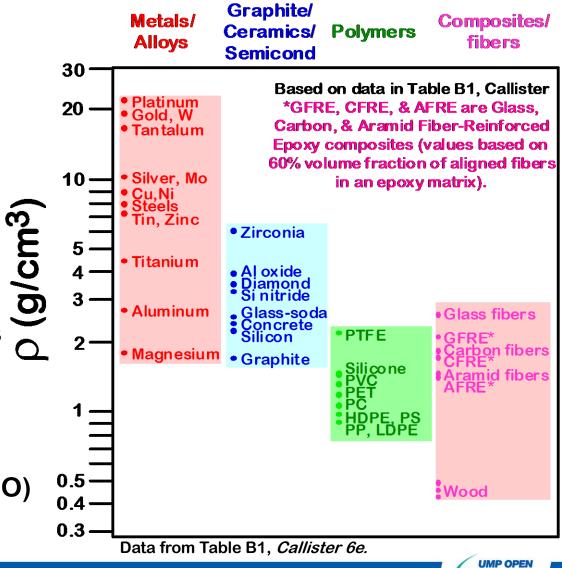
DENSITIES OF MATERIAL CLASSES 🚺



Why? Metals have...

- close-packing (metallic bonding)
- large atomic mass
 Ceramics have...
 - less dense packing (covalent bonding)
- often lighter elements Polymers have...
 - poor packing (often amorphous)
- lighter elements (C,H,O)
- Composites have...

intermediate values





Single crystal and polycrystalline materials

Single crystal \rightarrow Periodic and repeated arrangement of atoms is perfect or extends throughout the entirety of specimen without interruption.

Only 1 Crystal – environment must be carefully controlled

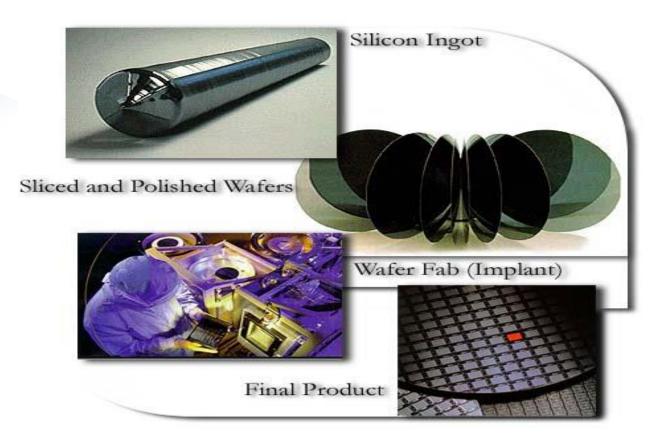
All unit cells interlock in the same way & have same orientation, geometry shape having flat surface.



Single crystal



Some engineering applications require single crystals:



Semiconductor- single crystal are necessary to allow electron flow more 'easily' w/out disturbance of grain boundaries





POLYCRYSTALS

Most engineering materials are polycrystals.
 Composed of collection of many small crystals or grain



Adapted from Fig. K, color inset pages of *Callister 6e*. (Fig. K is courtesy of Paul E. Danielson, Teledyne Wah Chang Albany)

• Crystal sizes typ. range from 1 nm to 2 cm (i.e., from a few to millions of atomic layers).



POLYMORPHISM AND ALLOTROPHY

POLYMORPHISM: Polymorphism is the ability of a solid material to exist in more than one form or crystal structure.

<u>Example</u>: Silica is known to form many polymorphs, the most important of which are; a-quartz, β -quartz, tridymite, cristobalite, coesite, and stishovite

ALLOTROPHY: Allotropy or allotropism is the property of some chemical elements to exist in two or more different forms. Example: Carbon, the allotropes of carbon include diamond (where the carbon atoms are bonded together in a tetrahedral lattice arrangement), graphite (where the carbon atoms are bonded together in sheets of a hexagonal lattice).

<u>Note</u>: Polymorphism and Allotropy are same thing. Polymorphism is used for compounds and the allotropy is reserved for elements.



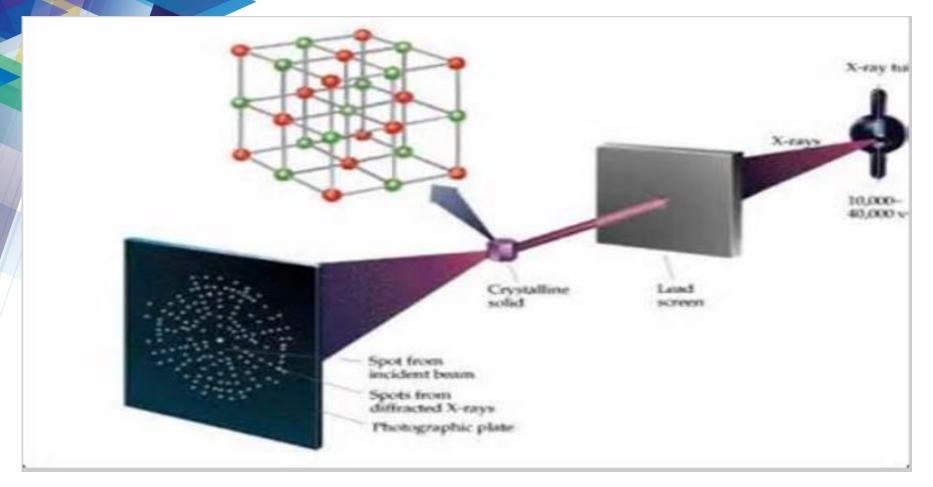


X-Ray Diffraction

How we identified this 'white powder'?







Why X-ray Diffraction (XRD)?

- We can understand atomic and molecular arrangements in solids.
 - Crystal structures & type of materials.
- We can development new materials





4. Imperfection in solids





Topic Contents

Introduction

- Solidification
- Microscopic Examination
- Point Defect
 - Vacancies and Self-Interstitials
 - Impurities in Solid
 - Specification of Composition
- Miscellaneous Imperfections
 - Dislocations Linear Defects
 - Interfacial Defects
 - Bulk or Volume Defects





INTRODUCTION

ISSUES TO ADDRESS...

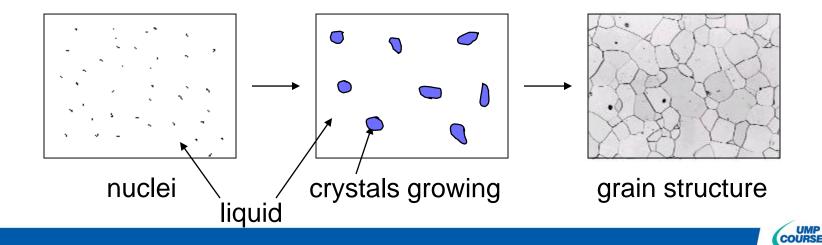
- What are the solidification mechanisms?
- What types of defects arise in solids?
- Can the number and type of defects be varied and controlled?
- How do defects affect material properties?
- Are ALL defects undesirable?



Solidification

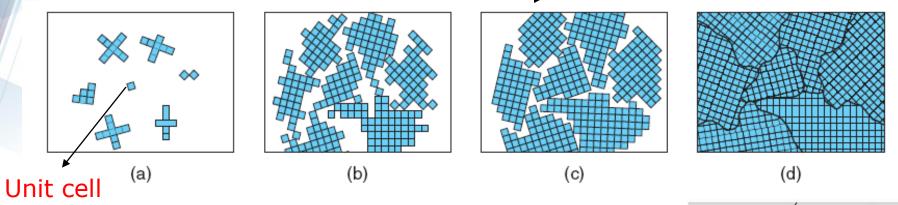


- The solidification of metal & alloy important industrial process
- Most metal are melted & then cast into semifinished or finished shape.
- Solidification- result of casting of molten material
 - Nuclei form
 - Nuclei grow to form crystals grain structure
- Start with a molten material all liquid
- Crystals grow until they meet each other



Stages of solidification of polycrystalline material

Cooling Process



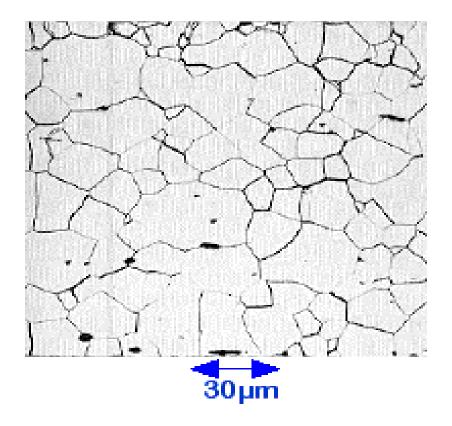
- a) Small crystallite nuclei (molten)
- b) Growth of the crystallites; the obstruction (block) of some grains that are adjacent to one another have formed
- c) Upon completion of solidification, grains (atomic mismatch) having irregular shapes have formed

d) The grain structure as it would appear under the microscope (dark lines are the grain boundary)





UMP OPEN



- Solidified metal containing many crystal is said to be polycrystalline.
- Number and size of the grains depends on the *rate* at which **nucleation** takes place
- The crystal in the solidified metal are called grains and the surface between them, grain boundaries.



Microscopic Examination

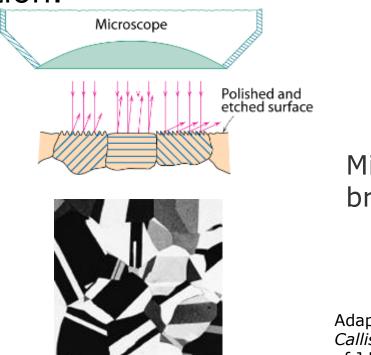
- Crystallites (grains) and grain boundaries. Vary considerably in size. Can be quite large
 - ex: Large single crystal of quartz or diamond or Si
 - ex: Aluminum light post or garbage can see the individual grains
- Crystallites (grains) can be quite small (mm or less)
 necessary to observe with a microscope.



Optical Microscopy



- Useful up to 2000X magnification.
- Polishing removes surface features (e.g., scratches); surface like mirror
- Etching changes reflectance, depending on crystal orientation.



0.75mm

Micrograph of brass (a Cu-Zn alloy)

Adapted from Fig. 4.13(b) and (c), *Callister 7e.* (Fig. 4.13(c) is courtesy of J.E. Burke, General Electric Co.

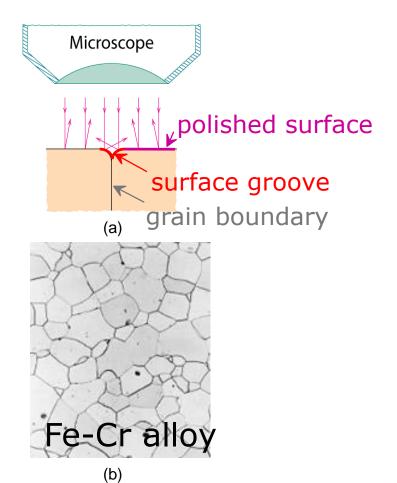




Optical Microscopy

Grain boundaries...

- may be revealed as dark lines,
- change in crystal orientation across boundary.







Electron Microscope

- Electron Microscope:
- i. The Scanning Electron Microscope (SEM)
- ii. Transmission Electron Microscopy (TEM)





i. The Scanning Electron Microscope (SEM)

- The upper limit of optical microscope ~2000x.
- but, some structural elements are too fine/small.
- need higher magnification
- An image of the structure under investigation is formed using beams of electrons instead of light radiation.
- The surface of a specimen to be examined is scanned with an electron beam, and the reflected (or back-scattered) beam of electron is collected, then displayed at the same scanning rate on a cathode ray tube (similar to a CRT TV screen)





- ii. Transmission Electron Microscopy (TEM)
- The image seen with a TEM is formed by an electron beam that passes through specimen.
- Details of internal microstructural features are accessible to observation
- Since solid materials are highly absorptive to electron beams, a specimen must be very thin.
- Magnification 1 000 000x are possible.





Imperfections in Solids

- Before this we assume the arrangement of atoms were perfect.
- But, in reality crystals are never perfect.
- Imperfection/defect affect many of their physical & mechanical properties.
- So, good or not to us?



• Example:

- Sterling silver (92.5% <u>Silver</u>, 7.5% <u>copper</u> (impurities)
- strong & hard compared to pure silver.





Types of Imperfections

- Vacancy atoms
- Interstitial atoms
- Substitutional atoms
- Edge dislocations
- Screw dislocations
- Mixed dislocations

Point defects

Line defects

Grain Boundaries

Interfacial / Area defects





1.0: Point Defects

- i. Vacancy
- ii. Self-interstitial
- iii. Substitutional

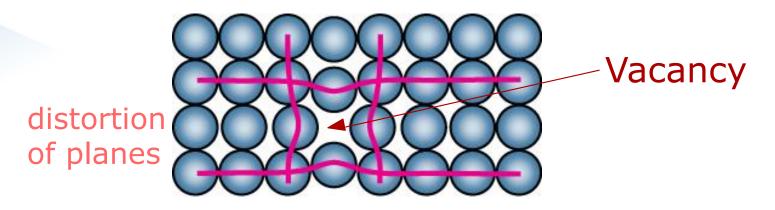






• Vacancies:

-vacant atomic sites in a structure.



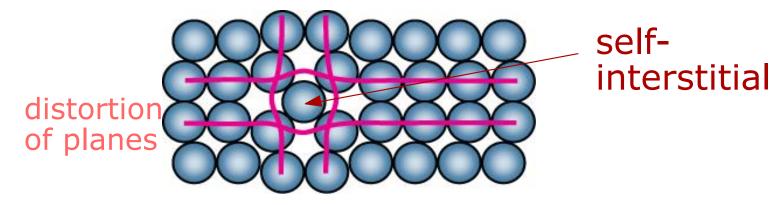
- The simplest of the point defect vacancy or vacant lattice site.
- One normally occupied from which an atom is missing
- All crystalline solids contain vacancies.
- Vacancies can moves and exchange site with neighbors

ii. Interstitials



Interstitials:

-"extra" atoms positioned between atomic sites.



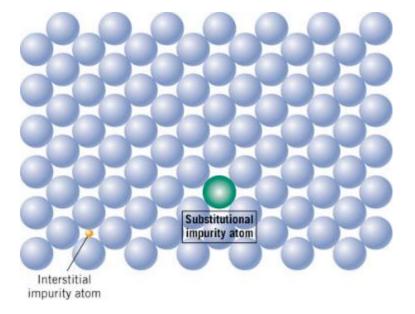
- An atom from crystal that is crowded into interstitial site.
- A small void space that under ordinary circumstances is not occupied. Impurities atoms fill the voids or interstices among the host atoms.
- In metal self-interstitial introduces relatively large distortions in the surrounding lattice.
- For metallic materials with high atomic packing factors interstitial relatively small.
- Example: carbon in FCC Iron atomic radius difference 42% but carbon can dissolved interstitially in iron



iii. Substitutional



Solute/impurity atom replace or substitute for the host atoms



Factors: (Hume-Rothery Rules)

- *i.* Atomic size factor impurity atom may be accommodated of solid solution only when the difference in atomic radii between the two types less \pm 15%.
- *ii. Crystal structure* for both atom types must be the same.
- *iii. Electronegativity* must be the same
- *iv. Valences* must be the same





Example:

A substitutional solid solution for Cu and Ni

	Си	Ni
Atomic Radius (nm)	0.128	0.125
Crystal Structure	FCC	FCC
Electronegativity	1.9	1.8
Valence	+1/+2	+2

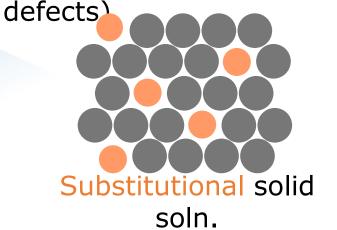


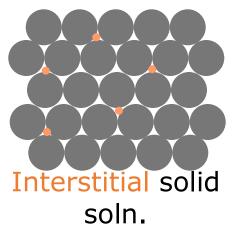
Examples:



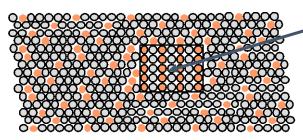
Two outcomes if impurity (B) added to host (A):
Solid solution of B in A (i.e., random dist. of point

OR





 Solid solution of B in A plus (e.g. C in Fe) phase (usually for a larger amount of B)



Second phase particle





2.0: Linear defects – Dislocations

Linear Defects (Dislocations)

- are one-dimensional defects around which atoms are misaligned
- slip between crystal planes result when dislocations move
- cause Lattice distortation

Schematic of Zinc (HCP):

- before deformation
- after tensile elongation
 slip steps

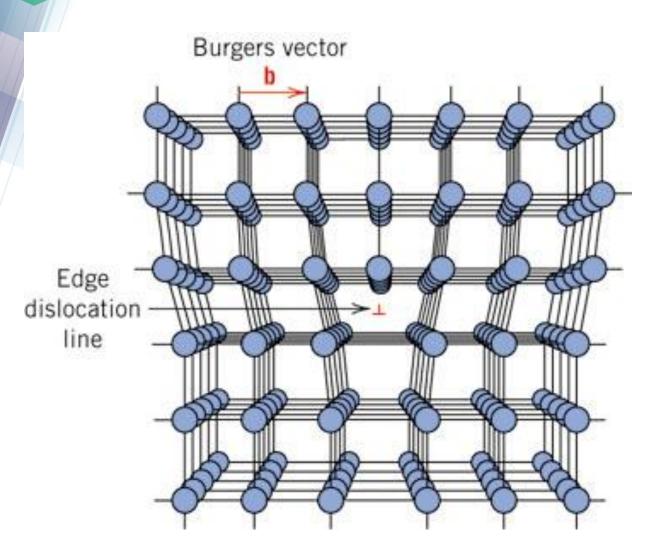
• Edge dislocation:

Adapted from Fig. 7.8, Callister 7e.

- extra half-plane of atoms inserted in a crystal structure
- Burger's factor, b \perp to dislocation line. \perp (tee :+ve edge dislocation line)
- Screw dislocation:
 - spiral planar ramp resulting from shear deformation
 - **b** || to dislocation line
- Mixed dislocation:
 - Combination of edge and screw dislocation

Edge dislocation

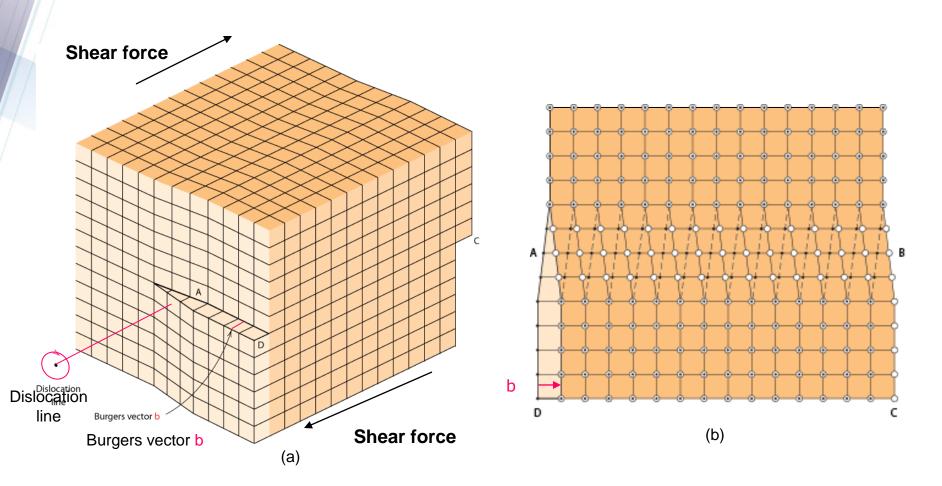




Burger's vector, b: measure of lattice distortion

Perpendicular to the edge dislocation line





Screw dislocation

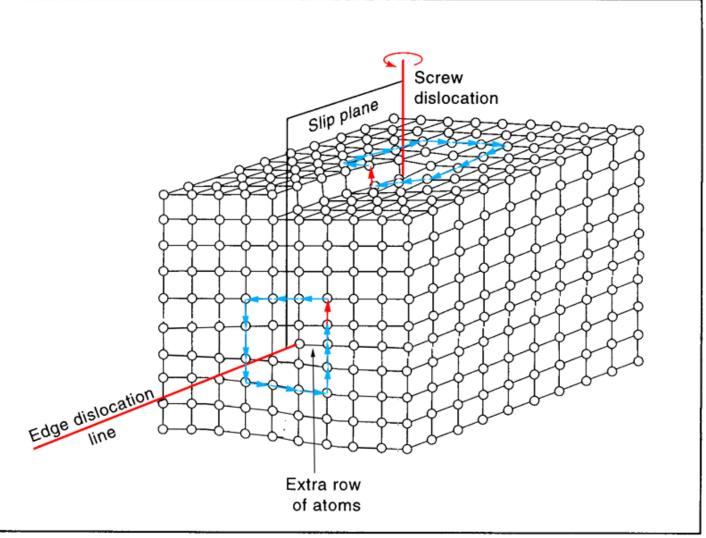
Screw Dislocation



Shifted one atomic distance (A-B)



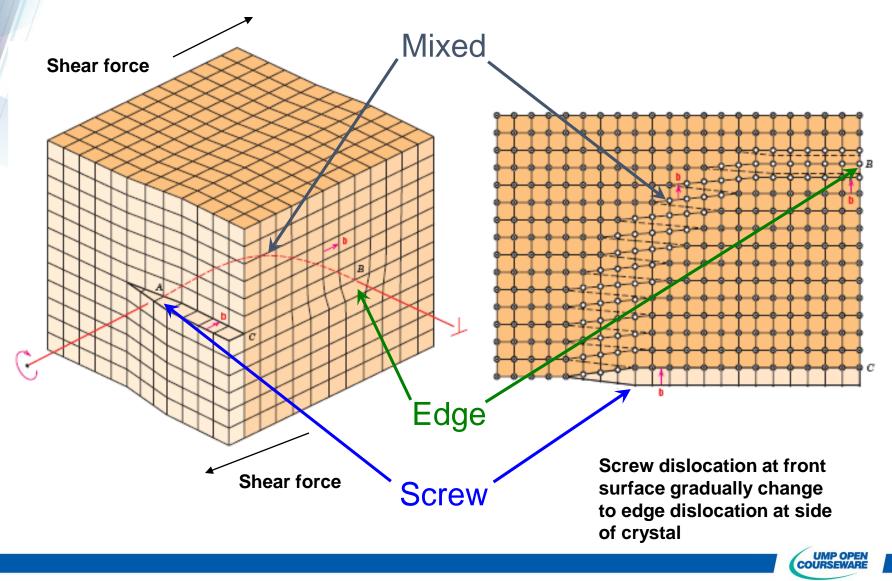




UMP OPEN COURSEWARE



Edge, Screw, and Mixed Dislocations



3.0: Interfacial / Area Defects:



 Grain boundary defect is a boundary that separate two small grains or crystals.

- Examples:
 - External surfaces, grain boundaries, twin boundaries, stacking faults and phase boundaries.

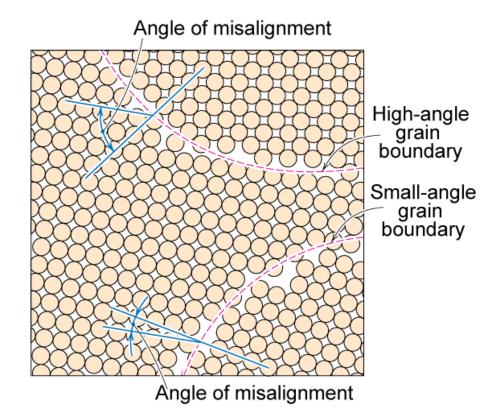


3.0: Interfacial / Area Defects:



Microstructure in atomic perspective

- regions between crystals
- transition from lattice of one region to that of the other
- slightly disordered
- Orientation mismatch (angle of misalignment)
- Small angle GB less surface energy, formed by edge & screw dislocation.



Adapted from Fig. 4.7, Callister 7e.





4.0: Bulk or Volume Defects

- These include pores, cracks foreign inclusion and other phases
- They are normally introduced during processing and fabrication steps.



Summary



- Point, Line, Area and Volume defects exist in solids.
- The number and type of defects can be varied and controlled (e.g., *T* controls vacancy conc.)
- Defects affect material properties (e.g., grain boundaries control crystal slip).
- Defects may be desirable or undesirable (e.g., dislocations may be good or bad, depending on whether plastic deformation is desirable or not.)

